



**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b>			
$V_{DSS}$	Drain-Source Voltage	75	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$ 5	A
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$ 10	A
		$T_C=100^\circ\text{C}$ 6.3	
$I_{DM}^a$	Pulsed Drain Current	$T_C=25^\circ\text{C}$ 40	
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$ 26	W
		$T_C=100^\circ\text{C}$ 10.4	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	4.8	$^\circ\text{C}/\text{W}$
$I_D$	Continuous Drain Current	$T_A=25^\circ\text{C}$ 3	A
		$T_A=70^\circ\text{C}$ 2.4	
$P_D$	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 2.5	W
		$T_A=70^\circ\text{C}$ 1.6	
$R_{\theta JA}^c$	Thermal Resistance-Junction to Ambient	50	$^\circ\text{C}/\text{W}$
$I_{AS}^b$	Avalanche Current, Single pulse	$L=0.5\text{mH}$ 5	A
$E_{AS}^b$	Avalanche Energy, Single pulse	$L=0.5\text{mH}$ 6.25	mJ

Note a : Pulse width limited by max. junction temperature.

Note b : UIS tested and pulse width limited by maximum junction temperature  $150^\circ\text{C}$  (initial temperature  $T_J=25^\circ\text{C}$ ).

Note c : Surface Mounted on  $1\text{in}^2$  pad area,

**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  Unless Otherwise Noted)

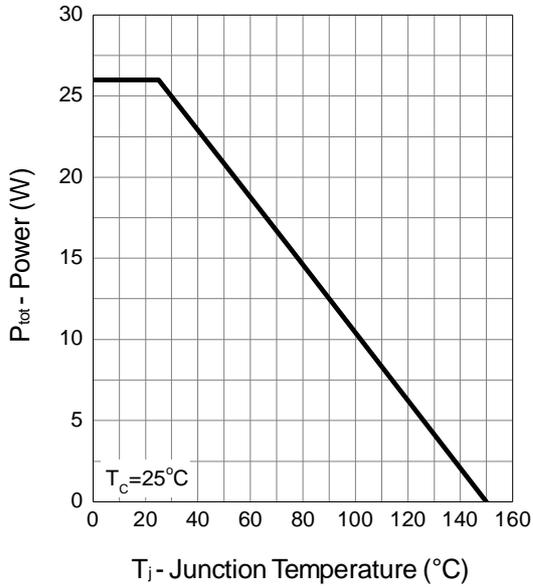
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	75	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=85^\circ C$	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1	2.3	3	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 10$	$\mu A$
$R_{DS(ON)}^d$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=5A$	-	110	132	$m\Omega$
		$V_{GS}=4.5V, I_{DS}=4A$	-	115	150	$m\Omega$
<b>Diode Characteristics</b>						
$V_{SD}^d$	Diode Forward Voltage	$I_{SD}=4A, V_{GS}=0V$	-	0.8	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=5A, dI_{SD}/dt=100A/\mu s$	-	20	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	20	-	nC
<b>Dynamic Characteristics<sup>e</sup></b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$	-	2.5	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=30V, Frequency=1.0MHz$	-	310	405	$pF$
$C_{oss}$	Output Capacitance		-	27	-	
$C_{rss}$	Reverse Transfer Capacitance		-	13	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=30V, R_L=30\Omega, I_{DS}=1A, V_{GEN}=10V, R_G=6\Omega$	-	9	17	ns
$t_r$	Turn-on Rise Time		-	7	13	
$t_{d(OFF)}$	Turn-off Delay Time		-	15	27	
$t_f$	Turn-off Fall Time		-	3	6	
<b>Gate Charge Characteristics<sup>e</sup></b>						
$Q_g$	Total Gate Charge	$V_{DS}=35V, V_{GS}=4.5V, I_{DS}=5A$	-	3	-	
$Q_g$	Total Gate Charge	$V_{DS}=35V, V_{GS}=10V, I_{DS}=5A$	-	7	10	
$Q_{gs}$	Gate-Source Charge		-	1.8	-	
$Q_{gd}$	Gate-Drain Charge		-	1.2	-	

Note d : Pulse test ; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

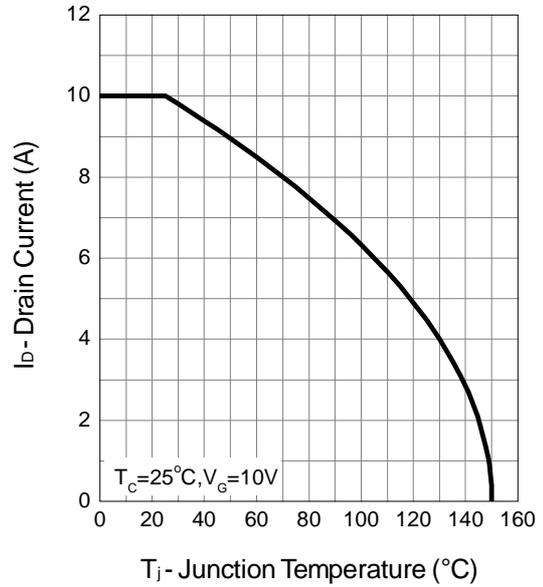
Note e : Guaranteed by design, not subject to production testing.

## Typical Operating Characteristics

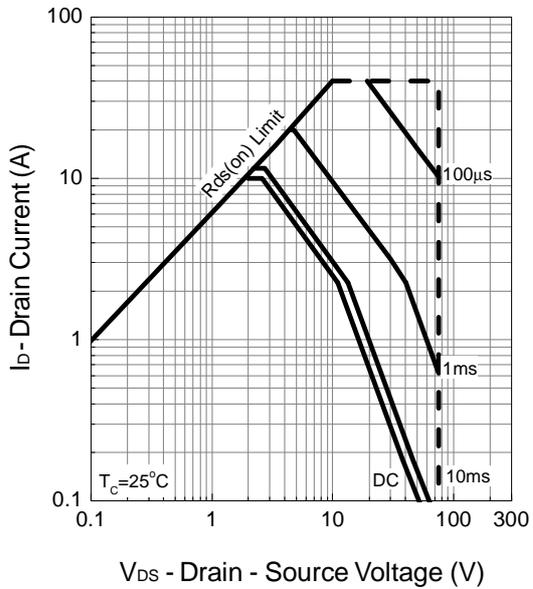
Power Dissipation



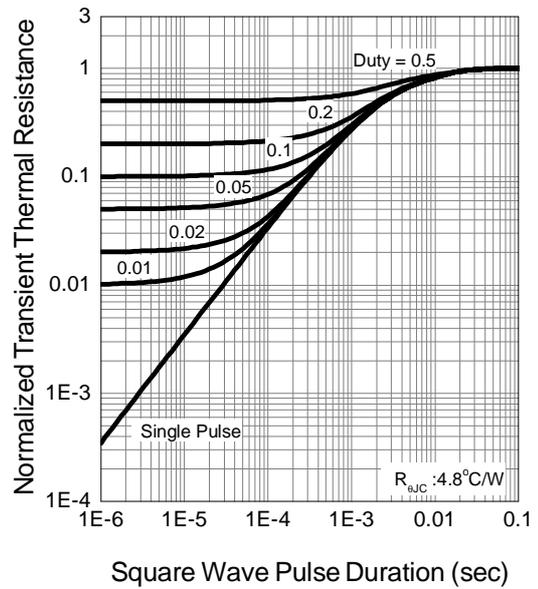
Drain Current



Safe Operation Area

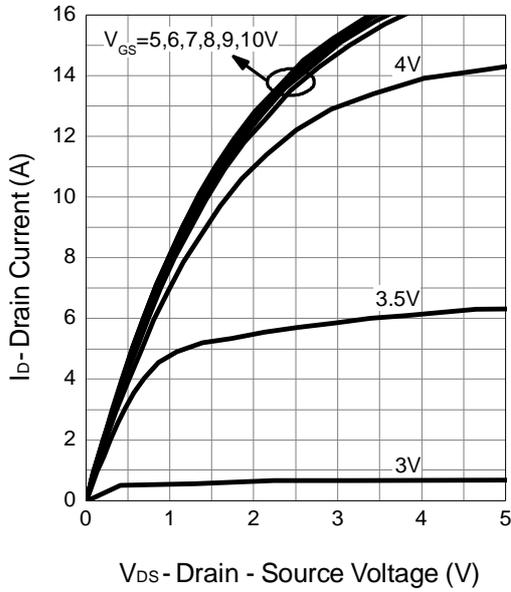


Thermal Transient Impedance

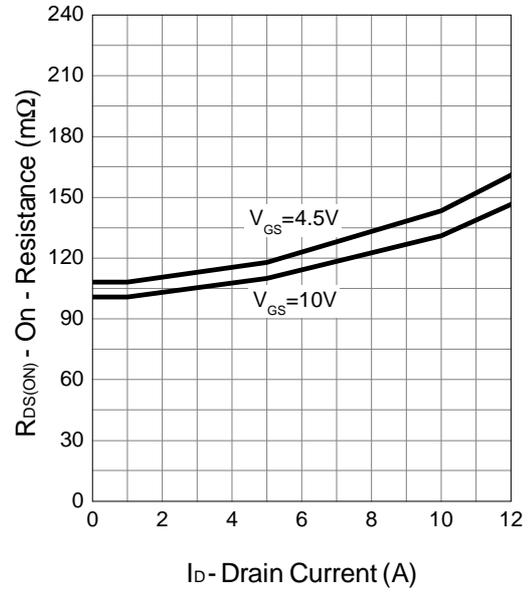


Typical Operating Characteristics (Cont.)

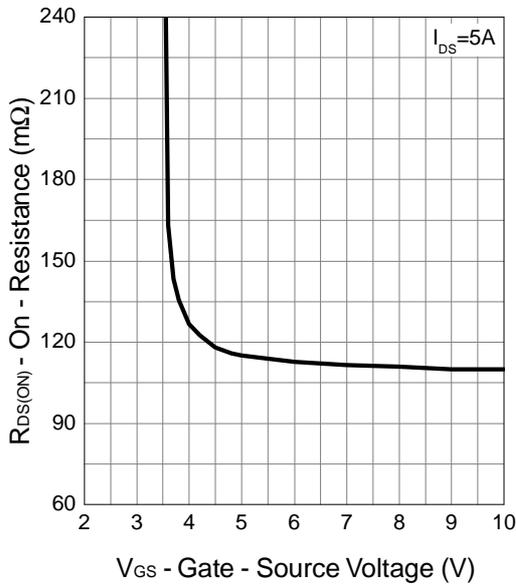
Output Characteristics



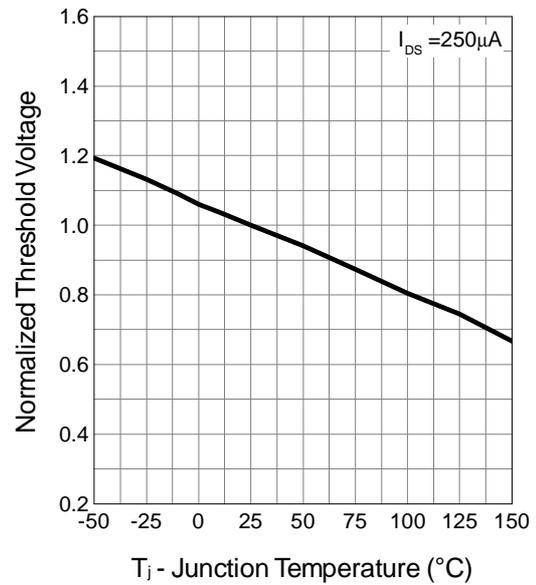
Drain-Source On Resistance



Gate-Source On Resistance

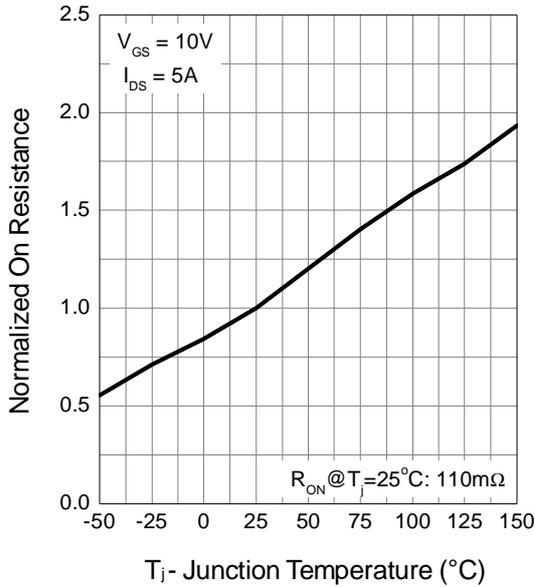


Gate Threshold Voltage

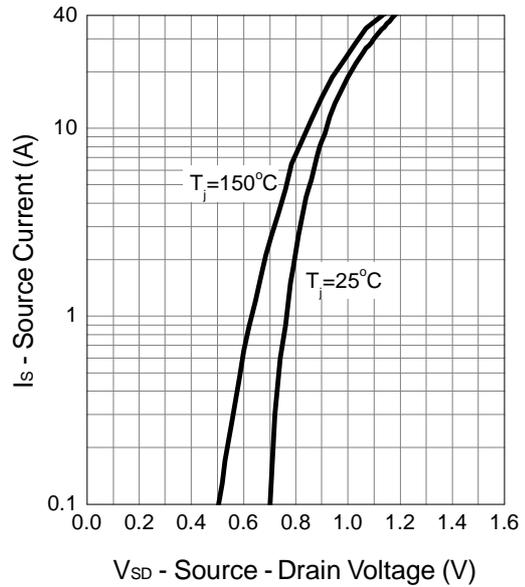


Typical Operating Characteristics (Cont.)

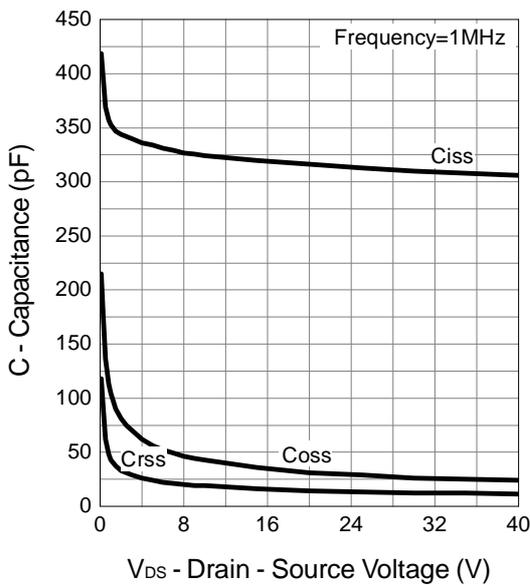
Drain-Source On Resistance



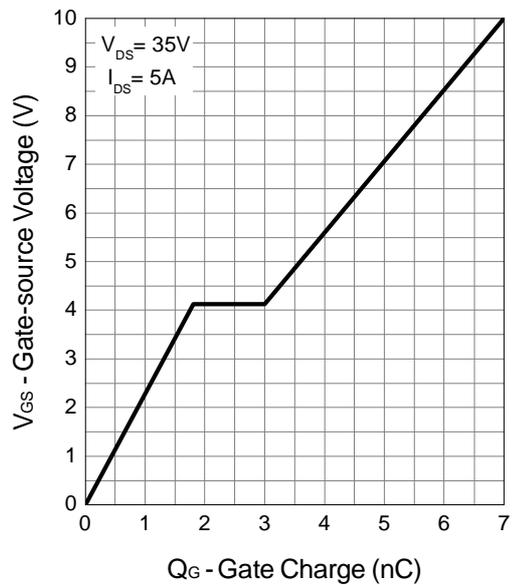
Source-Drain Diode Forward



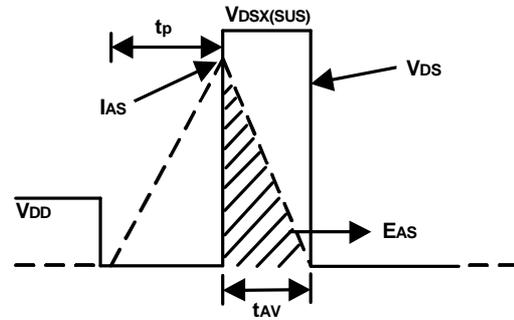
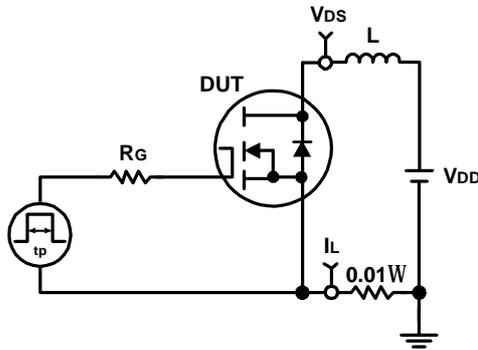
Capacitance



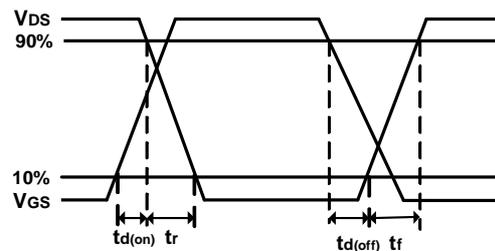
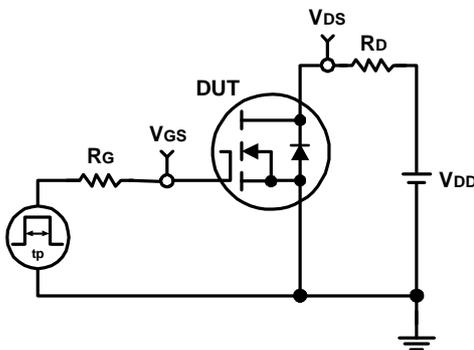
Gate Charge



### Avalanche Test Circuit and Waveforms

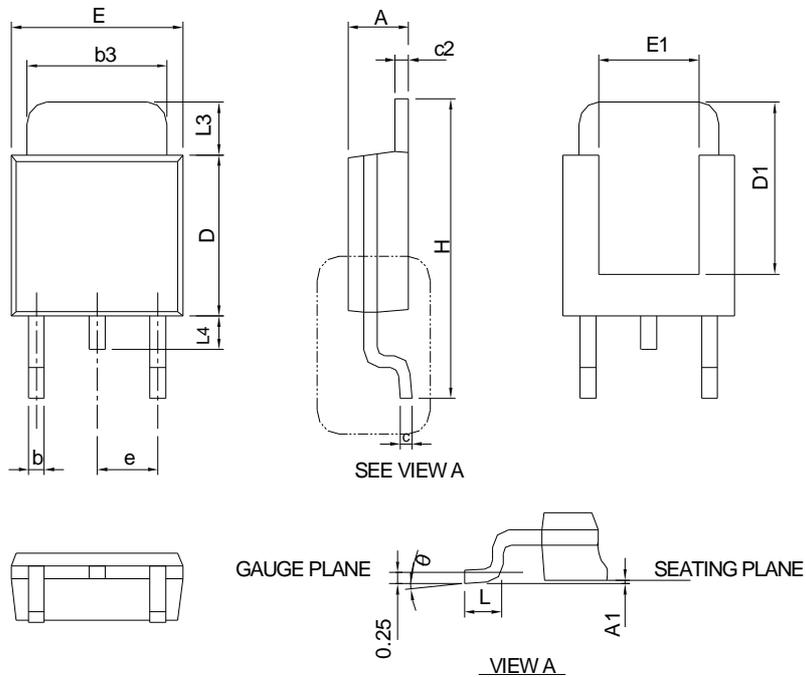


### Switching Time Test Circuit and Waveforms



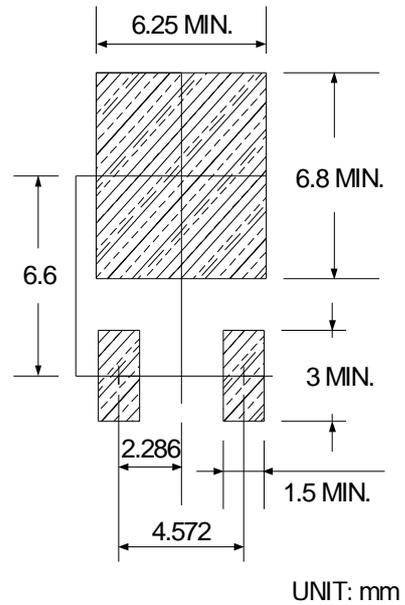
## Package Information

TO-252-3



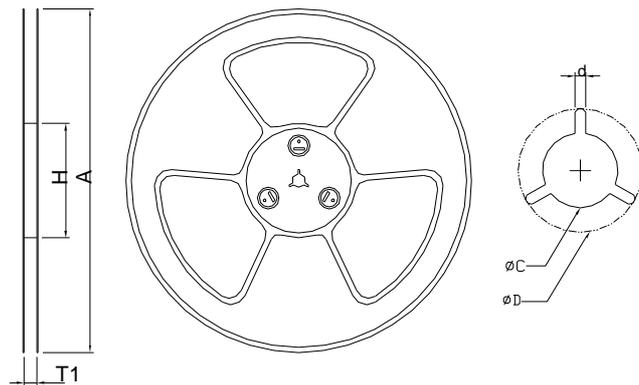
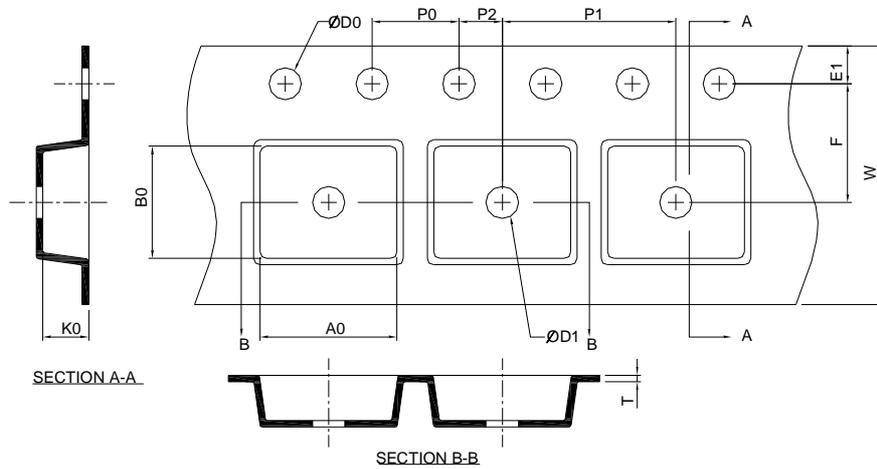
SYMBOL	TO-252-3			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1	-	0.13	-	0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4	-	1.02	-	0.040
θ	0°	8°	0°	8°

### RECOMMENDED LAND PATTERN



Note : Follow JEDEC TO-252 .

## Carrier Tape & Reel Dimensions

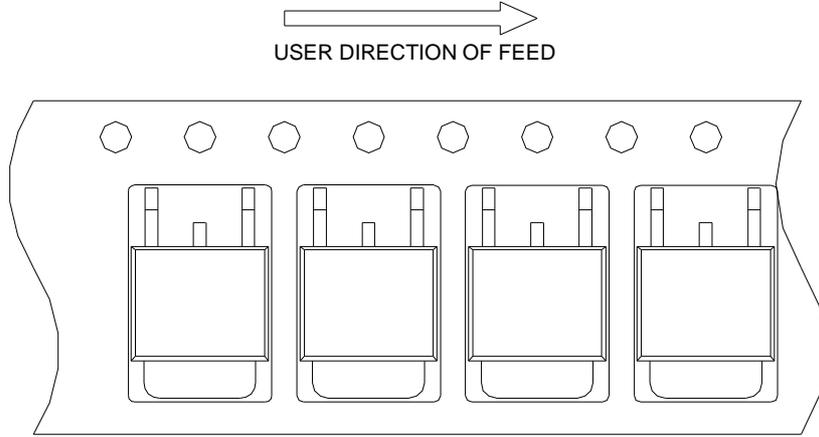


Application	A	H	T1	C	d	D	W	E1	F
TO-252-3	$330.0 \pm 2.00$	50 MIN.	$16.4 + 2.00$ $-0.00$	$13.0 + 0.50$ $-0.20$	1.5 MIN.	20.2 MIN.	$16.0 \pm 0.30$	$1.75 \pm 0.10$	$7.50 \pm 0.05$
	P0	P1	P2	D0	D1	T	A0	B0	K0
	$4.0 \pm 0.10$	$8.0 \pm 0.10$	$2.0 \pm 0.05$	$1.5 + 0.10$ $-0.00$	1.5 MIN.	$0.6 + 0.00$ $-0.40$	$6.80 \pm 0.20$	$10.40 \pm 0.20$	$2.50 \pm 0.20$

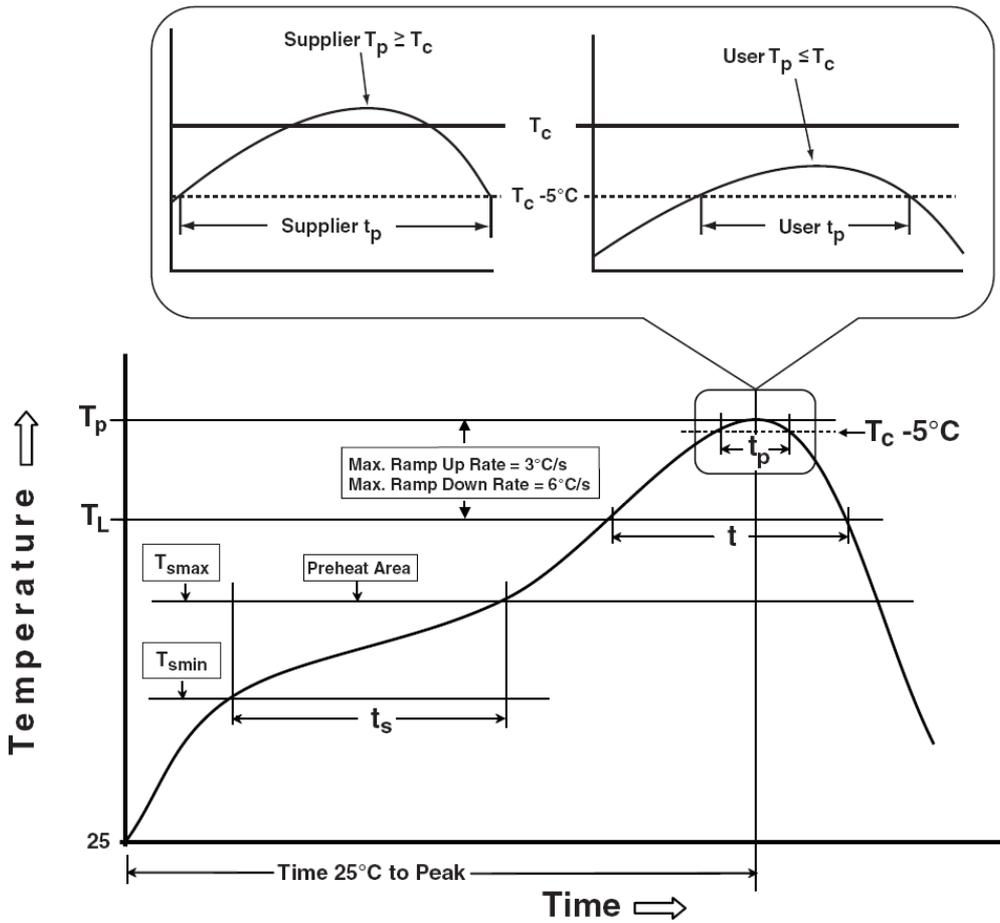
(mm)

## Taping Direction Information

TO-252-3



## Classification Profile



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## Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

## Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ $T_{jmax}$
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ $T_{jmax}$
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

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